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Cont replacement of adhesive layer 20 for reuse of typical carrier base 10. Such a combination adhesive preferably releases both chips and liner 10 without leaving a residue, and also preferably has greater adhesion to liner 10 than to the chip or other object carried so that the chip is released more easily than is the liner 10, i.e. it has a different release profile from the chip than from liner 10.

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Paragraph beginning at page 12, line 18:

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432 The second layer 30 of the adhesive laminate should be coated with a strong adhesive, e.g. about 100-5000 gm/inch, that will not be dramatically affected by thermal-UV or other radiation exposure. This second, non-curable adhesive layer 30 should be easily removable from the carrier base, so that the carrier base can be reused after application of a new adhesive laminate. Thus, second layer 30 has a different release profile than does first layer 20.

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Paragraph beginning at page 18, line 3:

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433 Alternatively and optionally, a cavity or window may be formed in a carrier structure 10 to allow energy (EMR) to pass through carrier base 15 to expose and cure the tacky layer 20 to achieve similar reduction of tackiness of the areas exposed. FIGURE 6 is an isometric schematic diagram of an exemplary embodiment of a carrier wherein a ledge 11 in the carrier structure 10 serves as a support for a radiation-transparent carrier base insert 15, upon which the adhesive layer 20 is disposed. Adhesive layer 20 may be any one of the two-layer, three-layer and four-layer embodiments described above. An object 60, such as a semiconductor chip or other electronic component is also shown in place on adhesive layer 20.

Alternatively, a transparent rigid backing substrate 15 may be used. The desirable characteristics of such a backing substrate 15 include transparency to the EMR that is used to cure the tacky layer, preferably transparency to UV, microwave or e-beam radiation. Suitable rigid backing substrates 15 include, for example, inorganic glasses such as quartz, silicate glasses or organic glasses such as polycarbonate, polystyrene, and acrylic. Desirably the rigid backing substrate 15 is low enough in cost so that it is

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cont

economically feasible to discard it after each use.

Paragraph beginning at page 18, line 19:

Also alternatively, and/or optionally, the laminate of adhesive layer 20 is protected from cross linking by UV light before the carrier structure is used by means of a UV barrier release liner 50. Typically, such release liner/cover 50 is placed over tacky layer 20 and over carrier base 15 to block EMR that would crosslink adhesive layer(s) 20 and will be removed from the UV curable tacky layer 20 prior to use. Such block may be restored or applied after the object 60 is placed on tacky layer 20 to block cross-linking EMR until such time as it is desired to release object 60. The carrier base platform 15 may be removable or non-removable from the waffle pack, tape-and-reel, and JEDEC tray configuration, as is desired.

Paragraph beginning at page 20, line 1:

All of these high-surface-energy polymers may be used for baking out moisture, e.g., at about 150°C. If extended exposure to higher temperature of about 200-350°C for a few minutes must be used, the more useful polymers will be those of polyvinylidene fluoride or its copolymer. Some of block co-polymers such as Kraton G series made by Shell Chemical Company or similar thermoplastic elastomer resin with high temperature stable backbone may be used. Preferably the adhesive has a higher and more permanent adhesion to the carrier base film or liner 10 than to the items to be carried, i.e. has a different release profile to carrier base film or liner 10 than to the items, and that the adhesive layer 20 be of sufficient thickness (typically about 1-5 mil) to hold parts with slightly different flatness tolerances.

#### IN THE CLAIMS:

Please rewrite claims 1, 2, 4, 10, 11, 13, 20, 21, 23 and 30 to read as follows:

1. (Amended) A re-usable carrier structure for carrying an article, comprising a carrier base having at least a portion thereof transparent to electromagnetic radiation,